

01-13-2003

File Docket No. 381NP/51553US

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102335563

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Yoshiyuki SASADA



2. Name and address of receiving party(ies)

Name: HITACHI, LTD.
Address: 6, Kanda Surugadai 4-chome,
Chiyoda-ku, Tokyo, Japan

1-6-03

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Execution Date: September 16, 2002

4. Application number(s) or patent number(s):

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A. Patent Application No.(s)
10/245,724

B. Patent No(s).

5. Name and address of party to whom
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CROWELL & MORING, L.L.P.
P.O. Box 14300
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6. Total number of applications and patents
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PATENT
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ASSIGNMENT

(譲渡証)

As a below named inventor, I hereby declare that:

IN CONSIDERATION of the sum of One Dollar (\$1.00) or the equivalent thereof, and other good and valuable consideration paid to me or us citizen(s) of Japan by HITACHI, LTD., a corporation organized under the laws of Japan, located at 6, Kanda Surugadai 4-chome, Chiyoda-ku, Tokyo, Japan, receipt of which is hereby acknowledged I do hereby sell and assign to said HITACHI, LTD., its successors and assigns, all my right, title and interest, in and for the United States of America, in and to

MOUNTING STRUCTURE OF HIGH-FREQUENCY SEMICONDUCTOR APPARATUS AND ITS PRODUCTION METHOD

invented by me or us and described in the application for United States Letters Patent therefor, executed on even date herewith, and all United States Letters Patent which may be granted therefor, and all divisions, continuations and extensions thereof, the said interest being the entire ownership of the said Letters Patent when granted, to be held and enjoyed by said HITACHI, LTD., its successors, assigns or other legal representatives, to the full end of term for which said Letters Patent may be granted, as fully and entirely as the same would have been held and enjoyed by me or us if this assignment and sale had not been made;

And I hereby agree to sign and execute any further documents or instruments which may be necessary, lawful, and proper in the prosecution of the above-named application or in the preparation and prosecution of any continuing, continuation-in-part, substitute, divisional, renewal, reviewed or reissue applications or in any amendment, extension, or interference proceedings, or otherwise to secure the title thereto in said assignee;

And I do hereby authorize and request the Commissioner of Patents to issue said Letters Patent to said HITACHI, LTD.

Signed on the date(s) indicated aside signatures:

INVENTOR(S)

(発明者フルネームサイン)

Date Signed

(署名日)

1) Yoshiyuki SASADA

Yoshiyuki Sasada

9/16/2002

2) _____

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